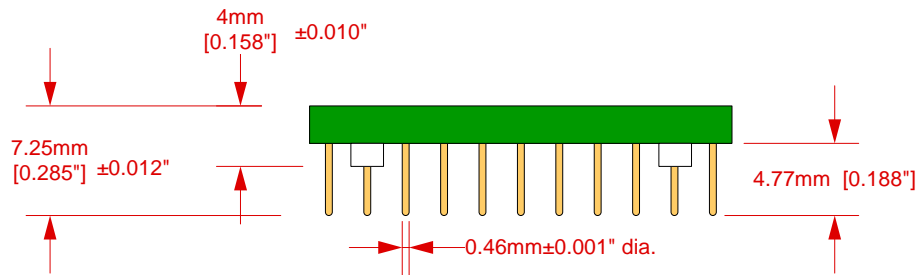
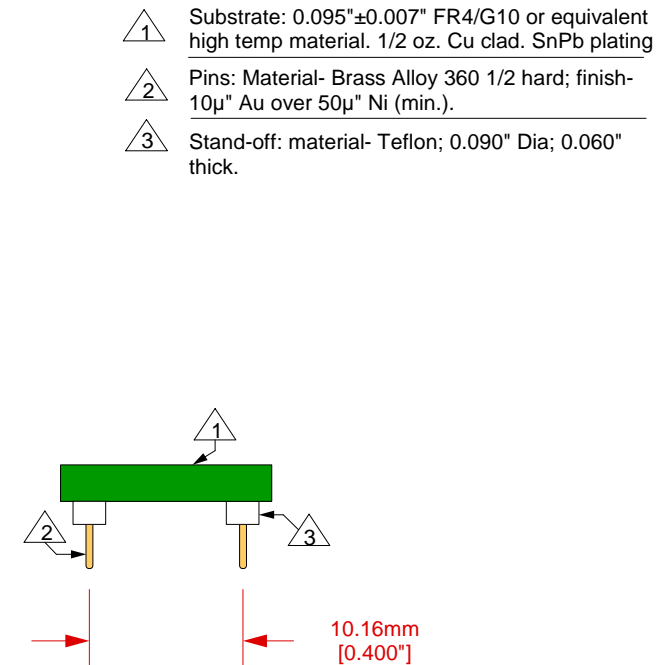


Top View



Side View




End View

- △1 Substrate: 0.095"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- △2 Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
- △3 Stand-off: material- Teflon; 0.090" Dia; 0.060" thick.

Description: PACKAGE CONVERTOR

24 position (0.050" pitch) SO surface mount land pattern to 22 position 0.400" wide DIP, round machined pins. This part is specifically mapped for the TI SN75ALS162DW to replace the TI SN75ALS162N.

	PC-SO/DIP-75162-01 Drawing	Status: Released	Scale: 2:1	Rev:B
	© 2001 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: J Cramer	Date: 1/26/01	
		File: PC-SO/DIP-75162-01 Dwg.mcd	Modified: 1/30/06, MT	

Tolerances: diameters ±0.03mm [±0.001"],
 PCB perimeters ±0.13mm [±0.005"],
 PCB thicknesses ±0.18mm [±0.007"],
 pitches (from true position) ±0.08mm [±0.003"],
 all other tolerances ±0.13mm [±0.005"]
 unless stated otherwise. Materials and
 specifications are subject to change without notice.